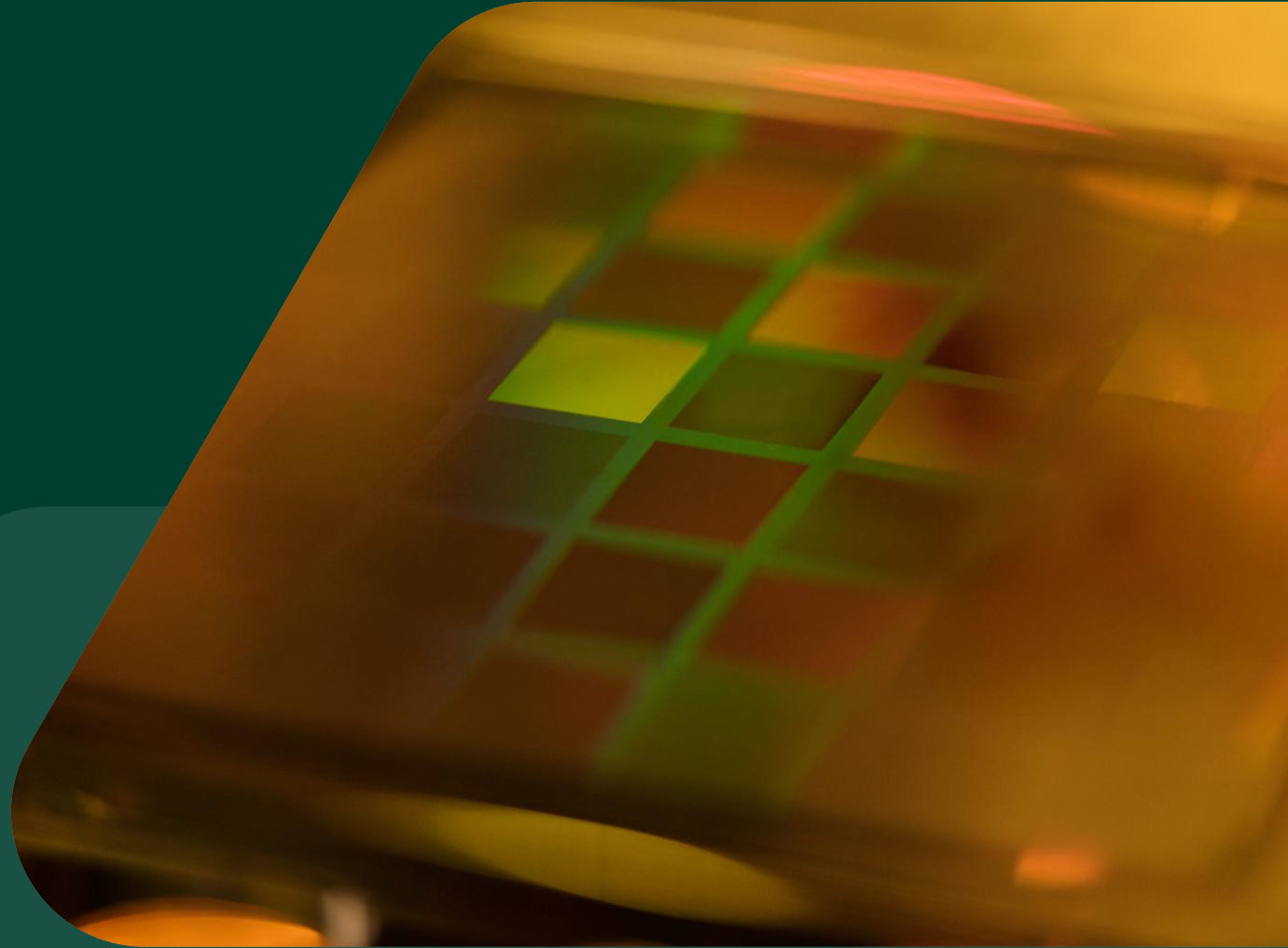


Business Unit Photomask Solutions (Yuta Nagai)



Agenda

01 **Market Outlook**

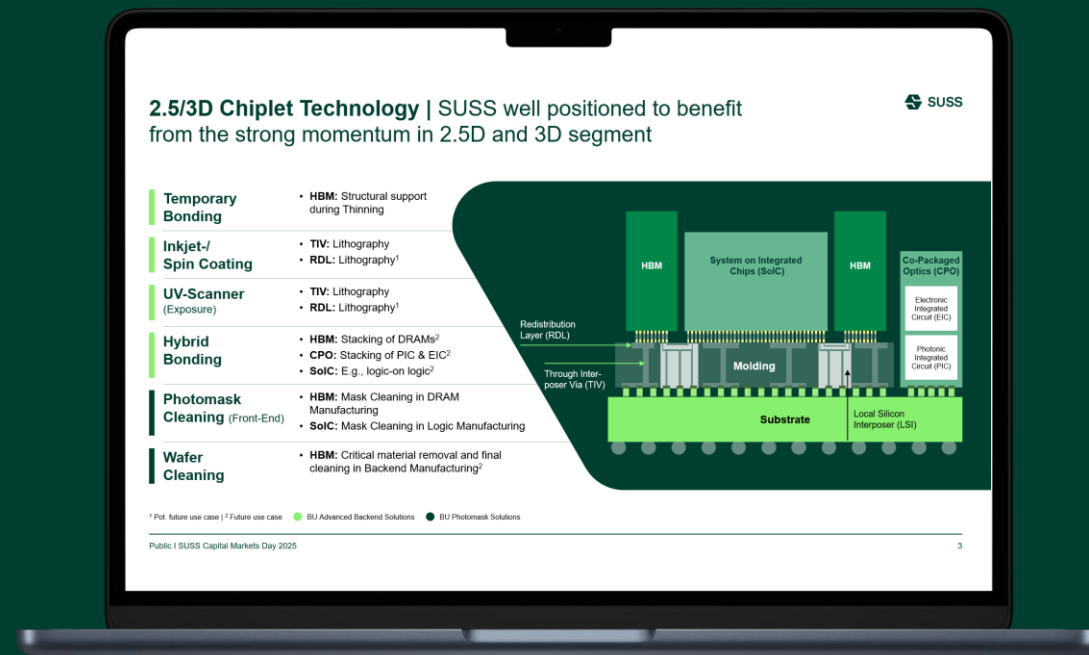
02 Vision & Strategy

03 Financial Highlights

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Synergies with Corporate Strategy and Our Strategic Role

Building the Foundation for Growth Across Front-End and Back-End







As **Moore's Law** continues to be extended, the demand for advanced photomasks remains solid. At the same time, demand in mature nodes is accelerating beyond 2025, requiring a **hybrid strategy** that addresses both segments.

Photomask Solutions will play a key role in supporting the corporate core strategy of expanding into next-generation **Backend applications** by strengthening its product portfolio to capture these emerging opportunities.

Global Evolution Driven by Moore's Law | Pushing the Boundaries of Semiconductor Technology with High-NA and Next-Gen Logic

imec



2023 N4/N3	2024 N3	2025 N3/N2	2026 N2	2027 N2/A14	2028 A14	2029 A14/A10	2030 A10
I3	I20A	I18A		I14A		I10A	
GAA FET 4nm/3nm		Ribbon GAA FET 1.8nm		Ribbon GAA FET 1.4nm		CFET 1.0nm	
EUV			High-NA EUV				
N3P/N3E	N2	N2P / A16		A14		A10	
FinFET 4nm/3nm		GAA NS-FET 2nm/1.6nm		GAA FET 1.4nm		CFET 1.0nm	
EUV				High-NA EUV			
SF3	SF2x	SF1.4x		???			
GAA FET 3nm		GAA FET 2nm		GAA FET 1.4nm		Next FET Gen 1nm	
EUV				High-NA EUV			
				N2	A14	A10	
				GAA FET 2nm		GAA FET 1.4nm CFET 1.0nm	
				EUV		High-NA EUV	
NXT 2100i		Next NXT Gen					
DUV (ArF): 1,35 NA							
NXE3600D	NXE 3800E				NXE:4000F		NXE:4200G
EUV: 0,33 NA							
	EXE 5000		EXE 5200B		EXE 5200C		EXE 5200D
	High-NA EUV: 0,55 NA						

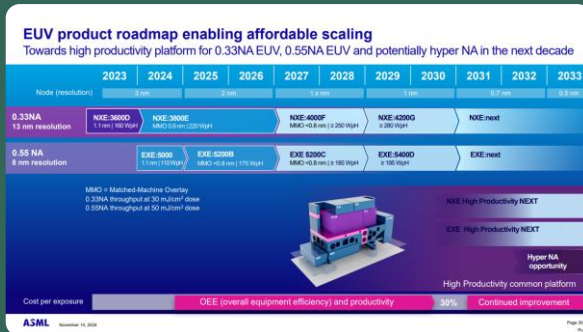
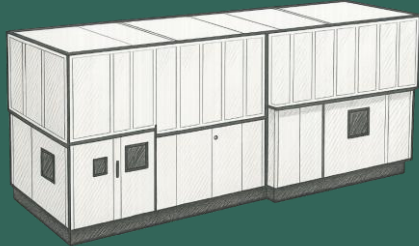
Source: Company Research & BNP Paribas Exane Estimates

Three Pillars of Future Technologies Driving Photomask Solutions

Shift from solely Scale-Determined to Function-Optimized Chip Design

1

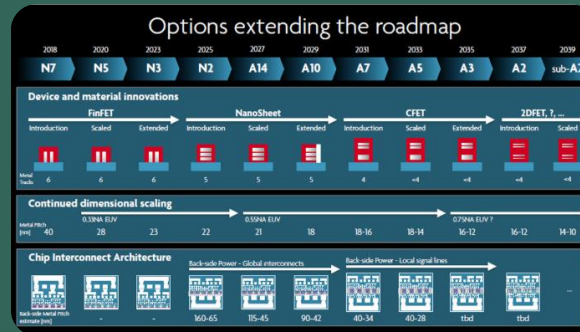
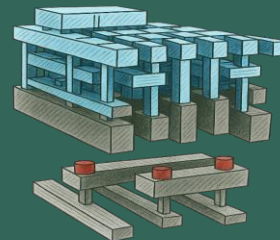
High-NA EUV



Source: ASML Investor Day 2024

2

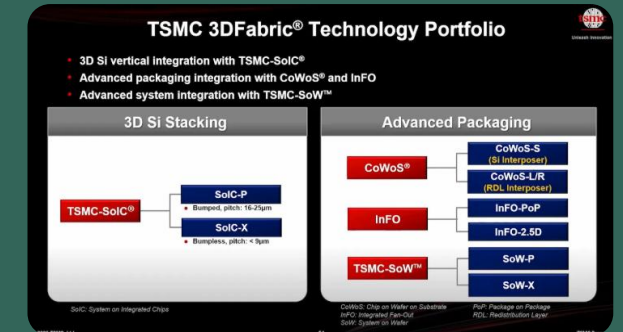
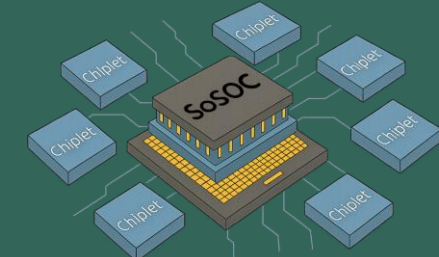
CFET – Transistor



Source: IMEC

3

Heterogeneous Integration



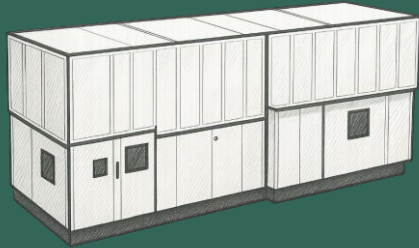
Source: TSMC 2025 Technology Symposium

Three Pillars of Future Technologies Driving Photomask Solutions

Shift from solely Scale-Determined to Function-Optimized Chip Design

1

High-NA EUV

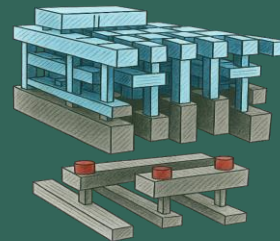


Higher resolution imaging

introduces new mask develop and cleaning challenges and potentially new Photomask formats

2

CFET – Transistor

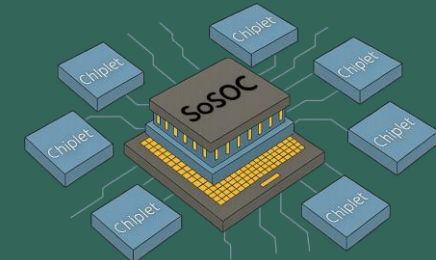


Vertical transistor stacking

increases number of lithography layers & number of high-end masks

3

Heterogeneous Integration



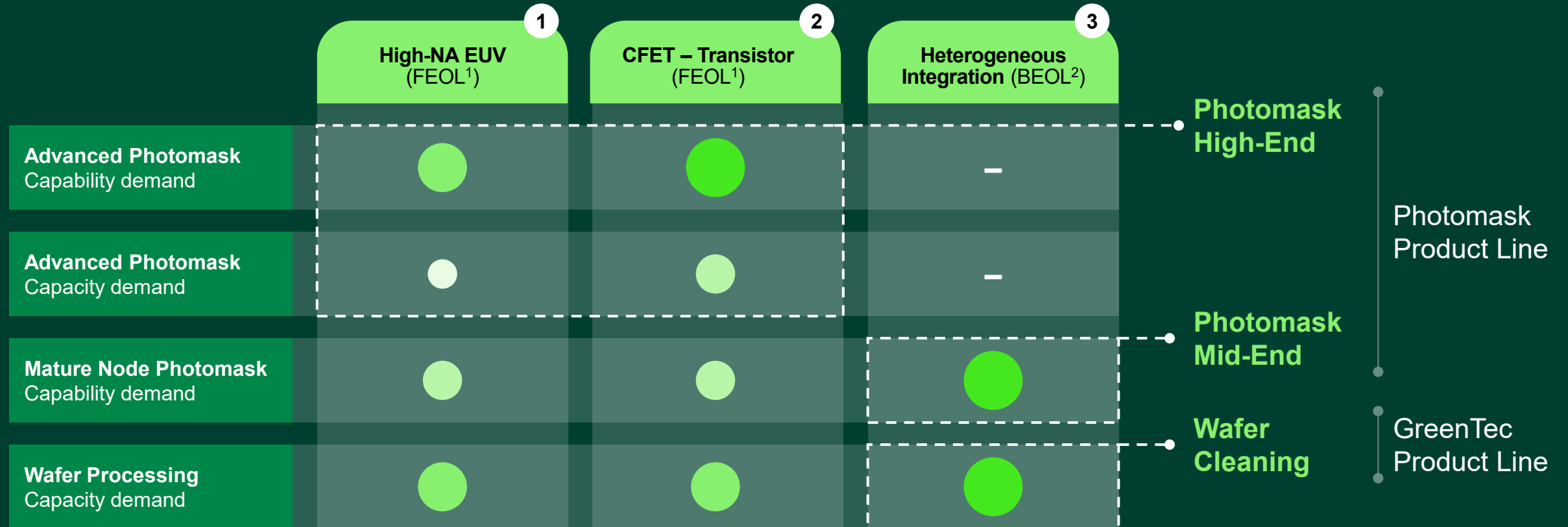
Disintegration into Chiplets

boosts wafer count and matured node Photomask usage

Three Pillars of Future Technologies Driving Photomask Solutions

Demand outlook 2030 – SUSS is well positioned across FEOL & BEOL

Market growth forecast 2025 – 2030



¹ Front-End of Line | ² Back-End of Line

● Demand growth very high
 ● Demand growth high
 ● Demand growth middle
 ● Demand growth low

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Strategy to Win | Leading the industry through cutting-edge technology & sustainable solutions

High-NA and **CFET** will set new **technology benchmarks**, while **Heterogeneous Integration** including Advanced Packaging drives **volume growth**



Market leader High-End Photomask cleaning: Committed to sustaining leadership through continuous innovation



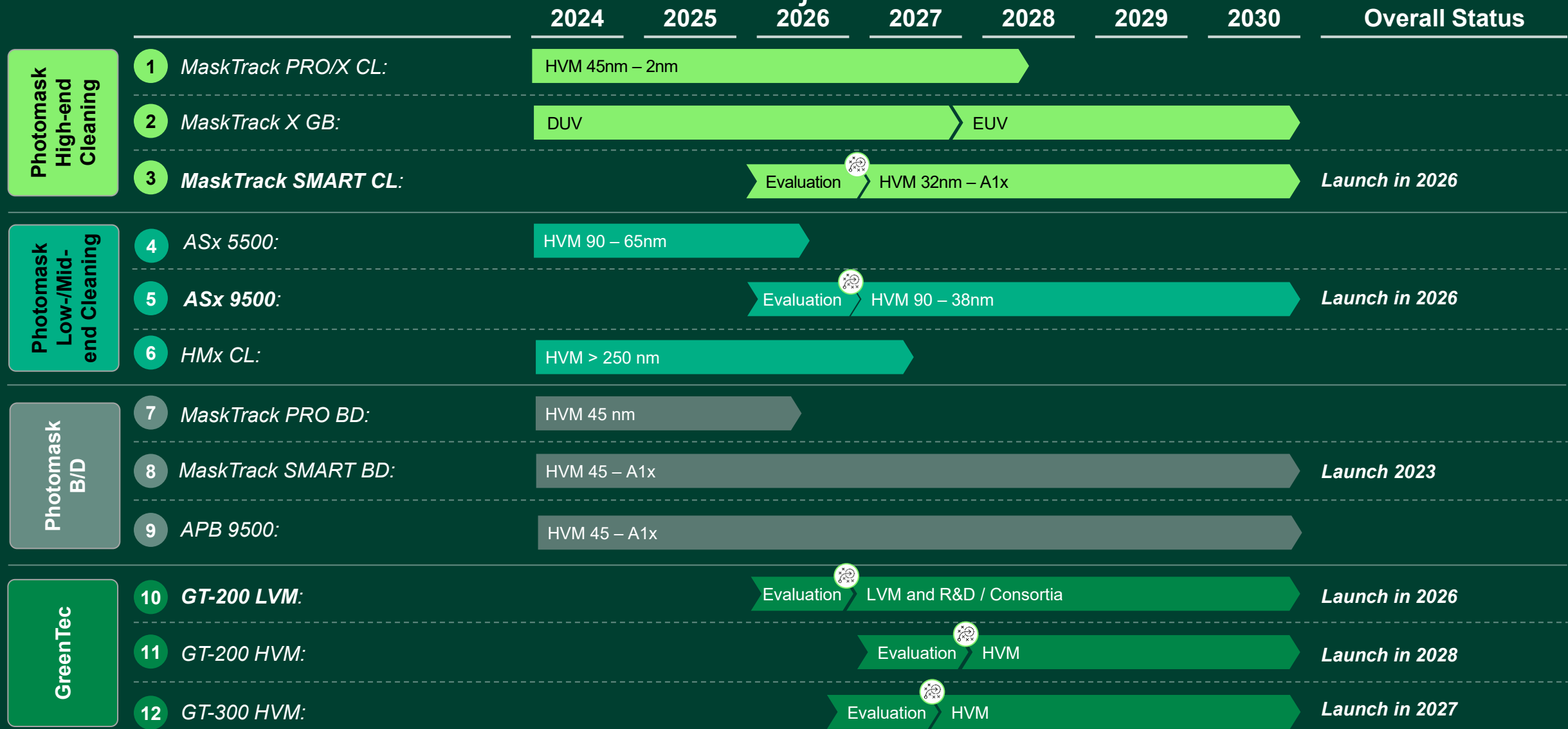
Strong position Mid-End Photomask cleaning: Relaunch of mid-end photomask tools to meet the growing needs of mature technologies



Enter Wafer Cleaning market: Launch wafer cleaning solutions for MEMS, Power, and CIS, paving the way to Advanced Packaging

Product Portfolio Roadmap

2026 will be a Milestone Year with three Major Product Launches



MaskTrack SMART Cleaning System | Expanding Hybrid Solutions from Optical Mask Technologies to High-NA EUV

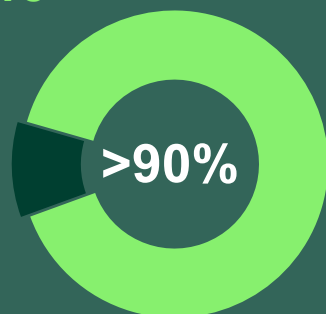
MaskTrack SMART Launch in 2026



SUSS Market share



2025



Target 2030

Superior particle removal through super high-frequency physical force cleaning

Gentle surface preparation through ICP Plasma¹ surface treatment

Optimized coverage and efficiency through 4 nozzles per chamber

Real-time tool performance optimization through SMART software

Scalable configuration with up to 5 process chambers

EUV mask backside-only cleaning capability

¹ ICP: Inductively Coupled Plasma

Photomask Cleaning Evolution in High-NA EUV Era | Tackling Shrinking CDs, 3D Mask Effects, Tight Overlay, High EUV Power and Zero Defect



1

Photomask Challenges

- **Anamorphic imaging**
Needs tighter CD and overlay tolerances for new masks
- **M3D *1 effects**
Use of new absorber materials to mitigate 3D mask issues
- **EUV pellicles**
Higher transmission and improved thermal stability
- **Defects & contamination**
Stronger control of particles and imperfections
- **Edge & reflectivity**
Stricter limits for black-border and edge performance and reflectivity losses caused by carbon and hydrocarbon

2

SUSS Excellence

- **Advanced particle removal control**
High-Frequency Megasonic and plasma-assisted cleaning
- **Use of EUV-compatible chemistry**
Formulated for multilayer mirrors and absorber stacks
- **Backside cleaning module**
Frontside protected backside cleaning
- **Ultra gentle frontside cleaning**
Local cleaning methods, ISUV technology
- **Automation & analytics**
Closed-loop control, smart predictive maintenance, pellicle-mounted mask handling

3

Competitive Advantage

- **Outstanding acknowledged process know-how**
Delivering unmatched precision and consistency
- **Proven field reliability EUV cleaning**
High-NA compliant photomask cleaning equipment
- **Partnerships with leading EUV key players**
With all fabs and Maskshop of the EUVL arena and equipment makers
- **Scalable platform design**
New platform prepared for new needed technologies and HVM

*1 M3D: Monolithic 3D

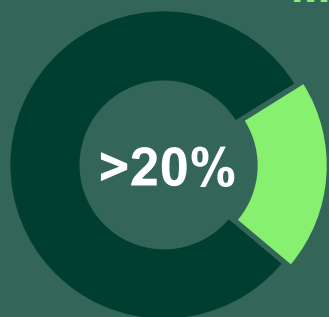
ASx9500 Cleaning System

A Scalable Mid-End Tool Configurable with only the Required Functions

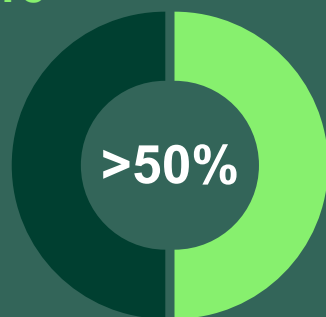
ASx9500 – Launch in 2026



SUSS Market share



2025



Target 2030

Scalable technology platform supporting technology nodes from 90 nm to 38 nm

Cost-efficient platform architecture enabling high productivity within a compact space

High performance and low operating cost through State-of-the-art Insite UV technology (acid-less process)

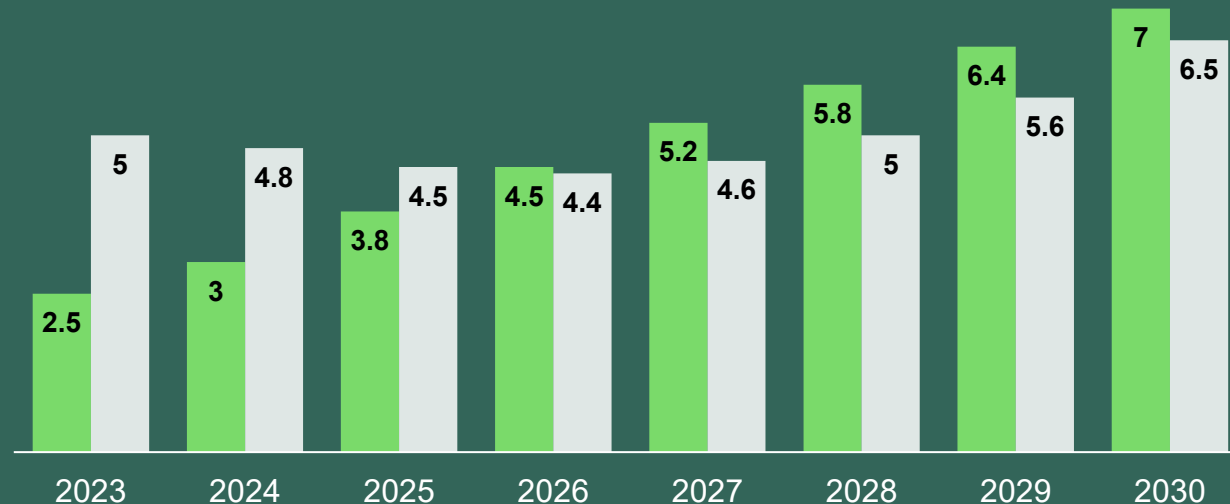
Optimized surface treatment through flexible physical force cleaning capability

Mature Node Growth Expected to More Than Double by 2030

Reaching Scale Comparable to High-End Nodes

Global Photomask Market Value by Technology Node (USD Billions, 2023 – 2030)

Market Value (USD Billions)



■ Mature Nodes (≥28nm) ■ Advanced Nodes (<14nm)

Market dynamics

- AI, Automation & IoT: Sustaining semiconductor demand
- China: Scaling mature nodes beyond 2027
- Heterogeneous integration drives a new wave of demands

Outlook

High photomask intensity at mature-node fabs offsets slower advanced-node spending, supporting continued market growth through 2030.

Overall Photomask Market Outlook 2027 – 2030

High-end demand is expected to rebound after 2027. Together, mature and High-end nodes are projected to fuel the photomask market's CAGR of approx. 7 – 8%.

GreenTrack Wafer Cleaning System | All-in-One Solution for Environmental Impact Reduction, TCO Improvement, and more



GreenTrack Wafer Cleaning – Launch in 2026



SUSS Market share



2025



Target 2030
(ramp-up phase)



Long-term
target

CrustBuster technology for advanced water-based cleaning

Sustainable processing through TurbulenStrip technology utilizing green fluids

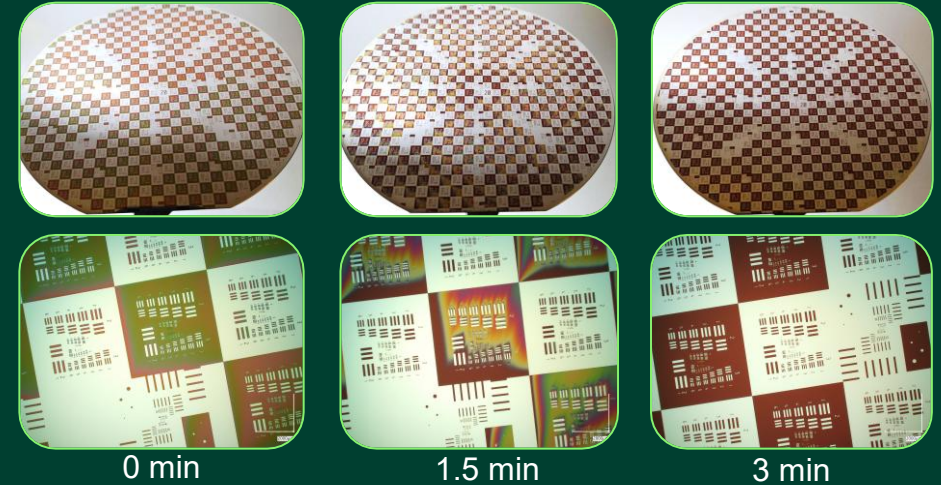
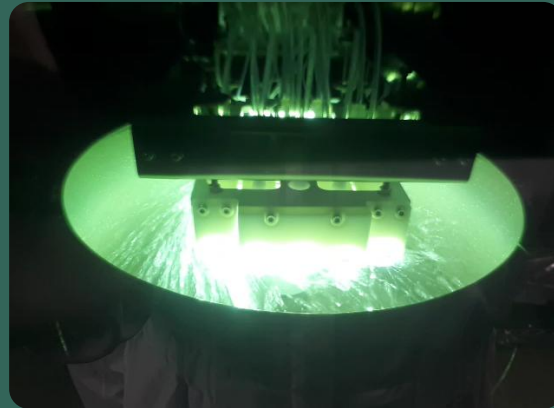
Batch and single-wafer processing enabled by hybrid design

Cost-efficient platform architecture leveraging strategic outsourcing

From Concept to Reality

Building Competitive Advantage Through Green Technology

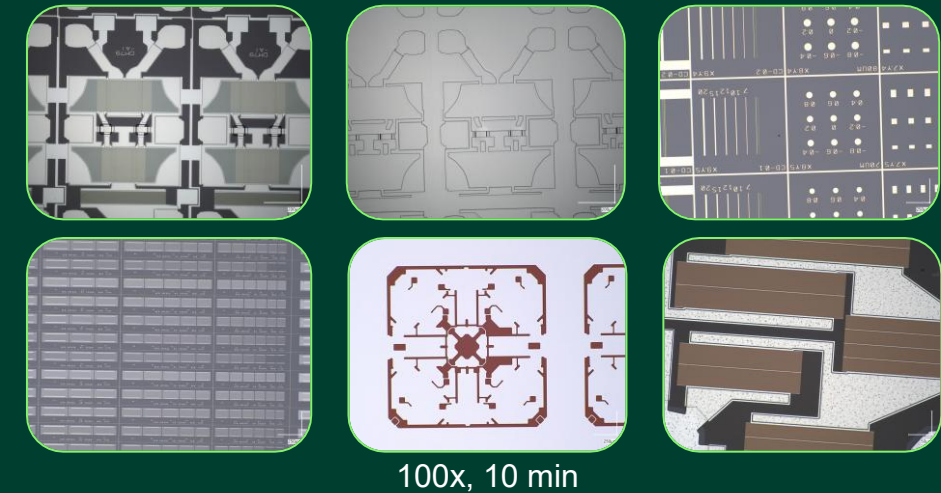
CrustBuster Technology



TurbulenStrip Technology

Green Fluids:

- High performance
- Water-based liquid
- Biodegradable
- Improved health and safety



GreenTrack Wafer Cleaning System | Strategic Entry into a Market Projected to Quadruple in SAM Alongside Product Launches



Green Track 200mm Launch 2026

Green Track 300mm Launch 2027

Source: SUSS Research based on Yole | Note: USD/EUR forward exchange rate = 1.18

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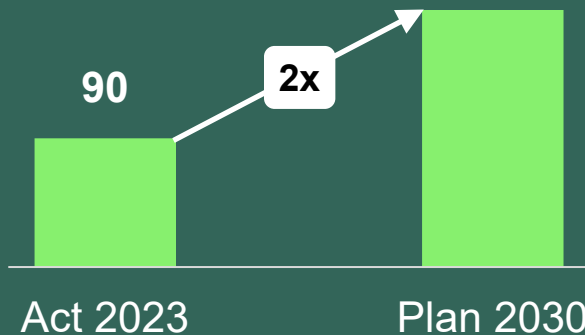
03 **Financial Highlights**

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Based on our strong execution since the last Capital Markets Day, we are now in a position to raise our revenue target for 2030

Capital Markets Day 2023

Revenue [€m]



We set a bold target – 2x revenue by 2030 through:

- Strategic market expansion
- Acceleration of GreenTec productization



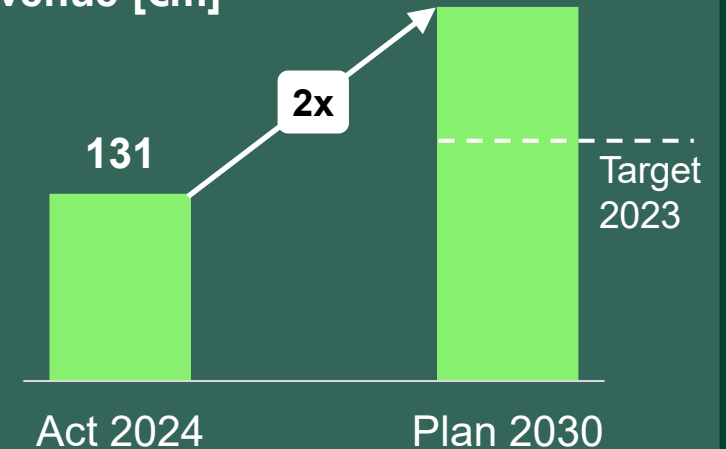
Accelerated execution

Technological innovation

Relentless drive toward sustainable leadership

Capital Markets Day 2025

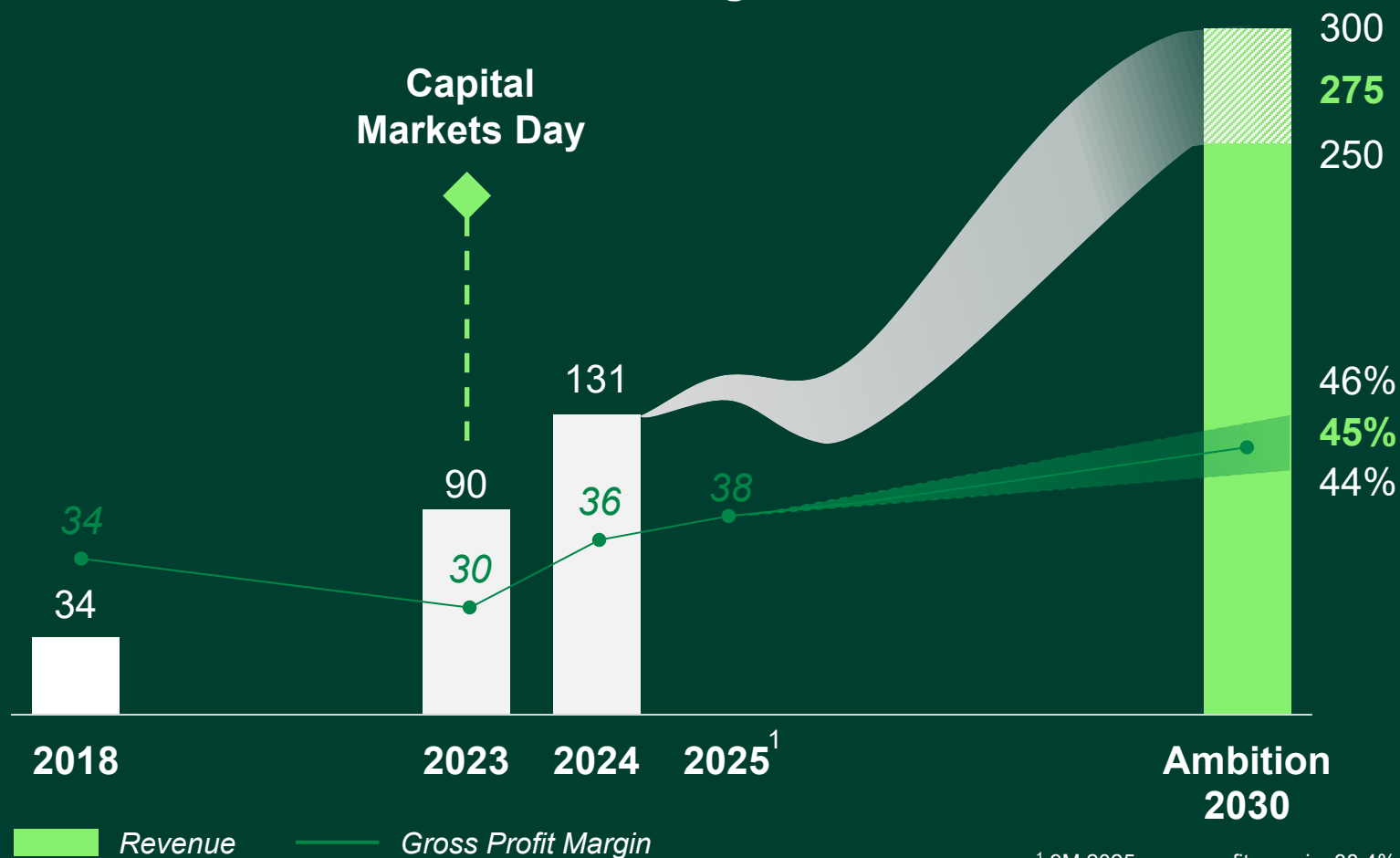
Revenue [€m]



Through rigorous execution, we **exceeded** our **2024 targets** even without GreenTec
We **raise our 2030 revenue ambition** to 2x 2024 levels

Revenue and Margin Outlook | Driving Growth through both Product Lines: Photomask and GreenTec

Revenue in €m & Gross Profit Margin in %



Key Takeaways

Photomask:

Revenue Outlook: 2026 will likely mark a short pause in growth as the industry enters a transition phase of the technology and investment cycle. With new equipment releases during this period, **accelerated sales growth** is expected after 2026.

GreenTec:

Revenue Outlook: During 2026–2027, we will be in the Go-to-Market phase, focusing on technology validation in the market. With the launch of our 300 mm tool from 2028 onward, we target to achieve revenue exceeding **€100 m** by 2030.

Gross Profit Margin Outlook:

We aim to achieve a gross profit margin target of **44 to 46%** through three key drivers:

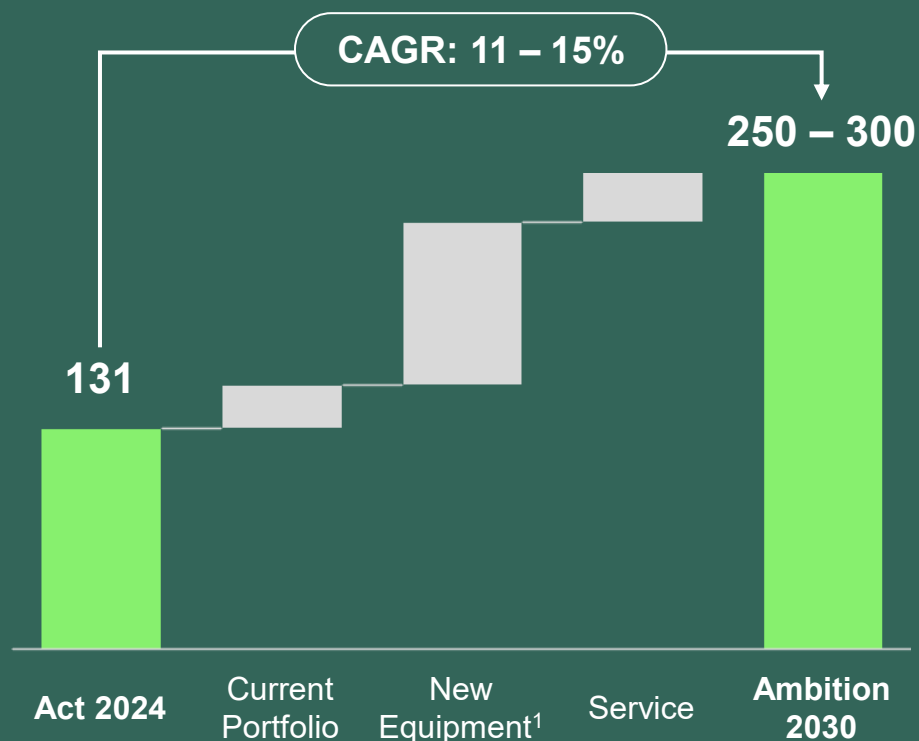
- Operational excellence
- Reduction of operational costs via outsourced manufacturing
- Improved pricing structure driven by the launch of new equipment

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- 02 Vision & Strategy
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- 04 **Summary**

Summary | Sustainable growth toward 2030 through Technology, Market Expansion, & Sustainability – expanding from mask to wafer cleaning

Revenue development (in €m)



Our Vision

Driving transformation and sustainable growth toward 2030 through **Technology, Market Expansion, and Sustainability**. We remain the No.1 provider in high-end photomask equipment and are expanding leadership into mid-end and GreenTec solutions.

Product Roadmap Highlights

2026 marks a milestone year with three major launches:

- MaskTrack SMART Cleaning
- ASx9500
- GreenTrack 200 LVM

Financial Highlights – Ambition 2030

- Sales: €250–300m
- Gross Profit Margin: 44 to 46%

¹ GreenTrack Wafer Cleaning

Disclaimer

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Forward-looking statements are based on current plans, estimates, projections and expectations and are therefore subject to risks and uncertainties, most of which are difficult to estimate and which in general are beyond the control of SUSS MicroTec SE. Consequently, actual developments as well as actual earnings and performance may differ materially from those which explicitly or implicitly assumed in the forward-looking statements.

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